

Title (en)

A moderate pH electrolyte bath for electroplating.

Title (de)

Elektrolytisches Bad mit mässigem pH-Wert für das Elektroplattieren.

Title (fr)

Bain électrolytique à pH modéré pour l'électroplacage.

Publication

EP 0265588 A1 19880504 (EN)

Application

EP 87107032 A 19870514

Priority

US 91404586 A 19861001

Abstract (en)

An aqueous electrolyte bath for electroplating a tin-lead alloy onto a substrate contains a tin salt and a lead salt of alkanesulfonic acid of 1-4 carbons, a conductivity enhancer of an alkali, alkaline earth, or tetraalkylammonium salt of an alkanesulfonic acid of 1-4 carbons, and a grain refiner; the pH of said bath is adjusted between about 1 and the pH at which tin or lead hydroxide begins to precipitate out due to reaction with one or more bases of alkali, alkaline earth, or tetraalkylammonium hydroxide, oxide, or carbonate. A tin-lead alloy solder is electroplated onto a substrate, such as glass or ceramics, in an electrolytic process by impressing an electromotive force across such an aqueous electrolyte bath between electrodes until the substrate has been plated.

IPC 1-7

C25D 3/60; **C25D 5/54**

IPC 8 full level

C25D 3/60 (2006.01); **C25D 5/54** (2006.01)

CPC (source: EP US)

C25D 3/60 (2013.01 - EP); **C25D 5/54** (2013.01 - EP US)

Citation (search report)

- [Y] FR 2534279 A1 19840413 - OBATA KEIGO [JP], et al
- [Y] PATENT ABSTRACTS OF JAPAN, vol. 9, no. 78 (C-274)[1801], 6th April 1985; & JP-A-59 211 562 (MITSUBISHI DENKI K.K.) 30-11-1984

Cited by

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EP 0265588 A1 19880504; BR 8705055 A 19880524; DK 513787 A 19880402; DK 513787 D0 19870930; JP S6389695 A 19880420

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